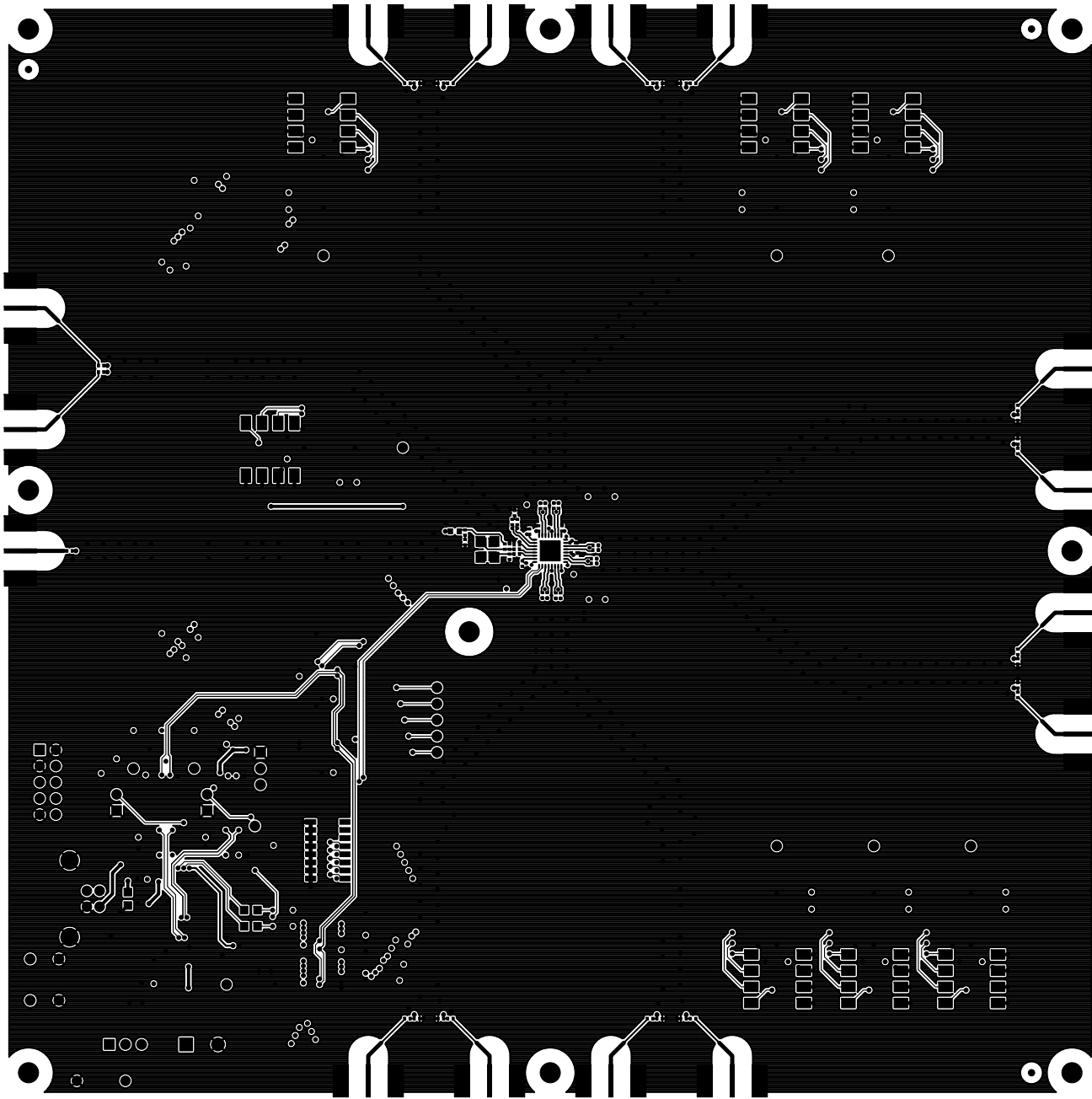
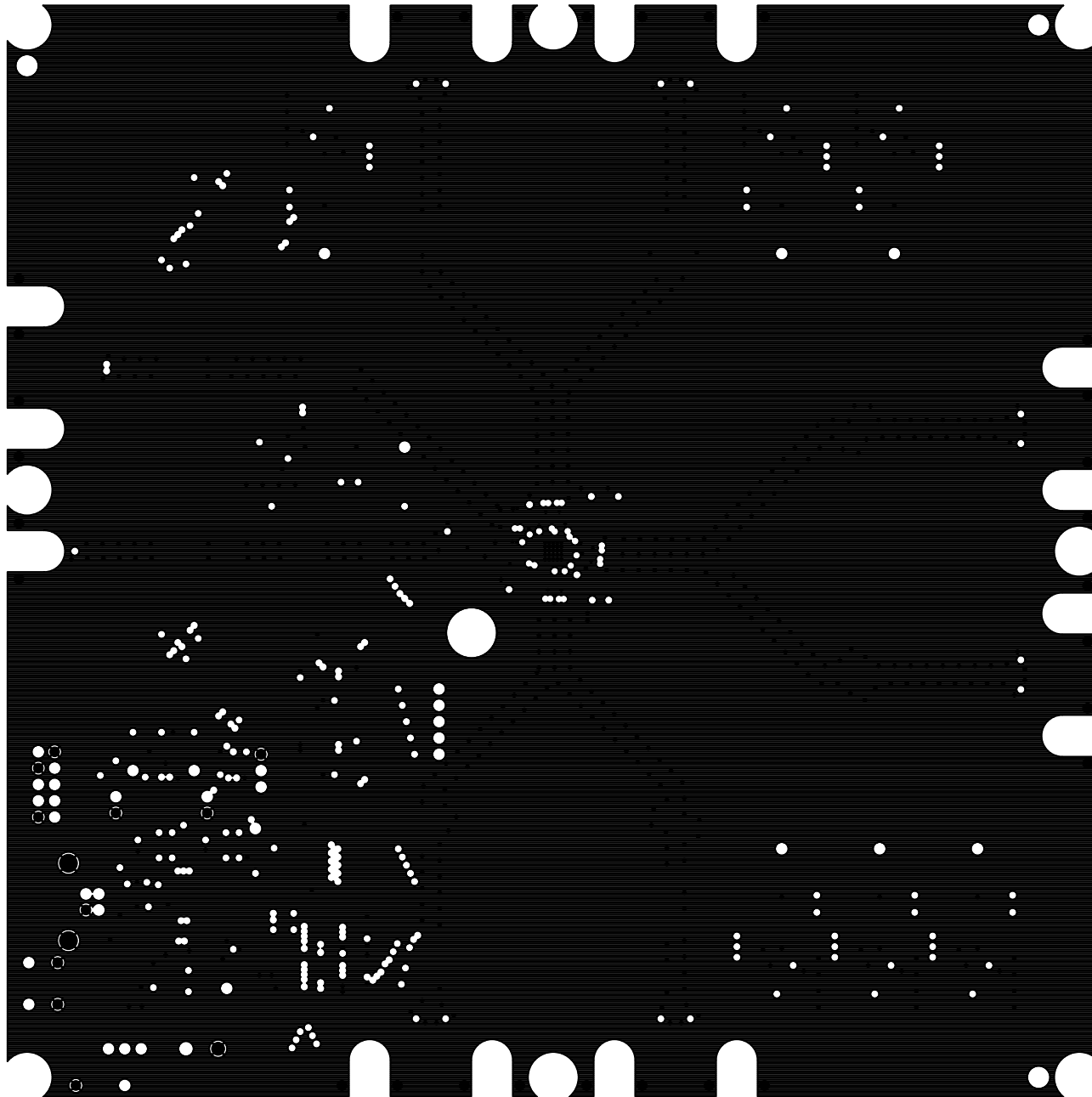
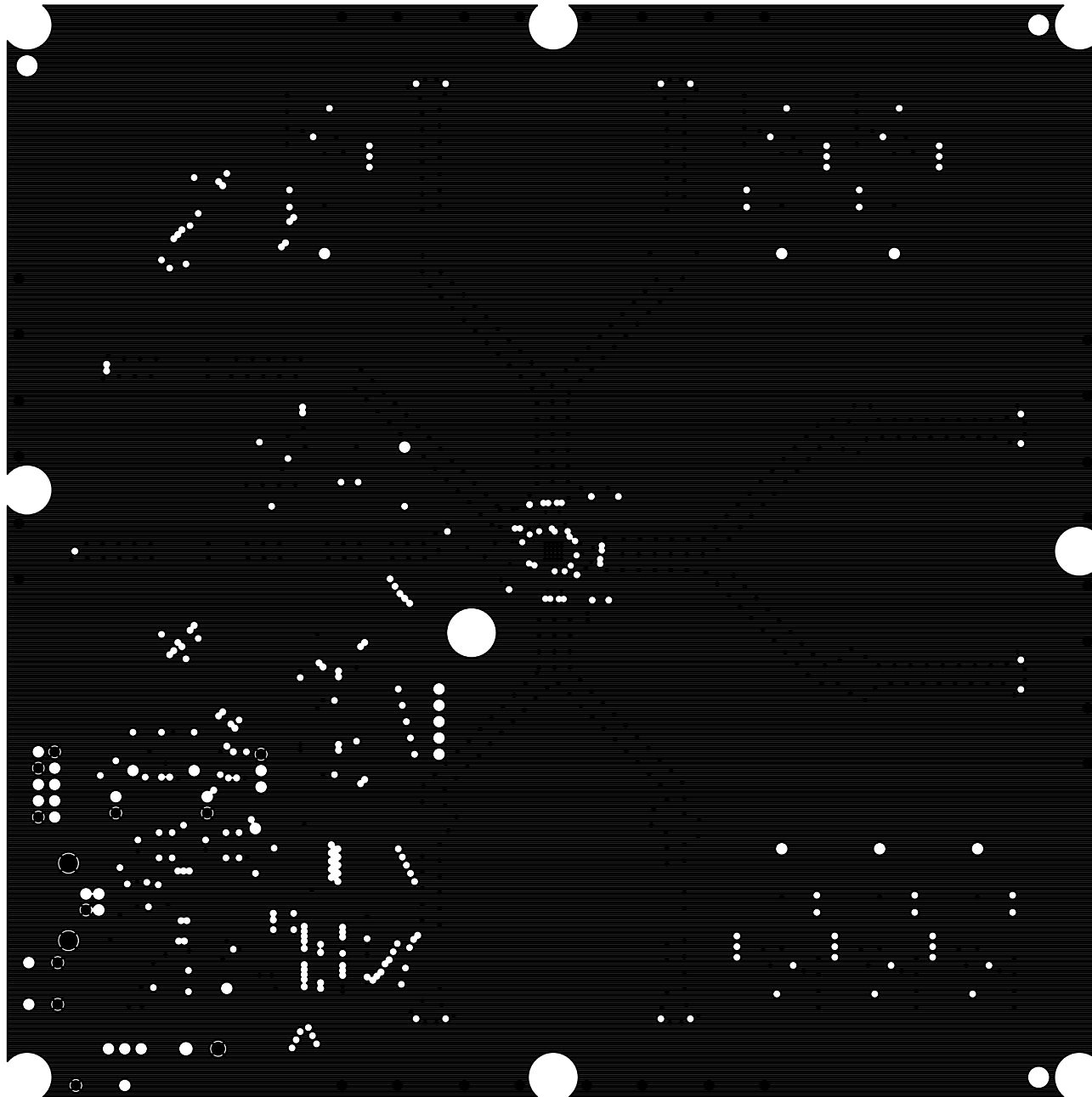


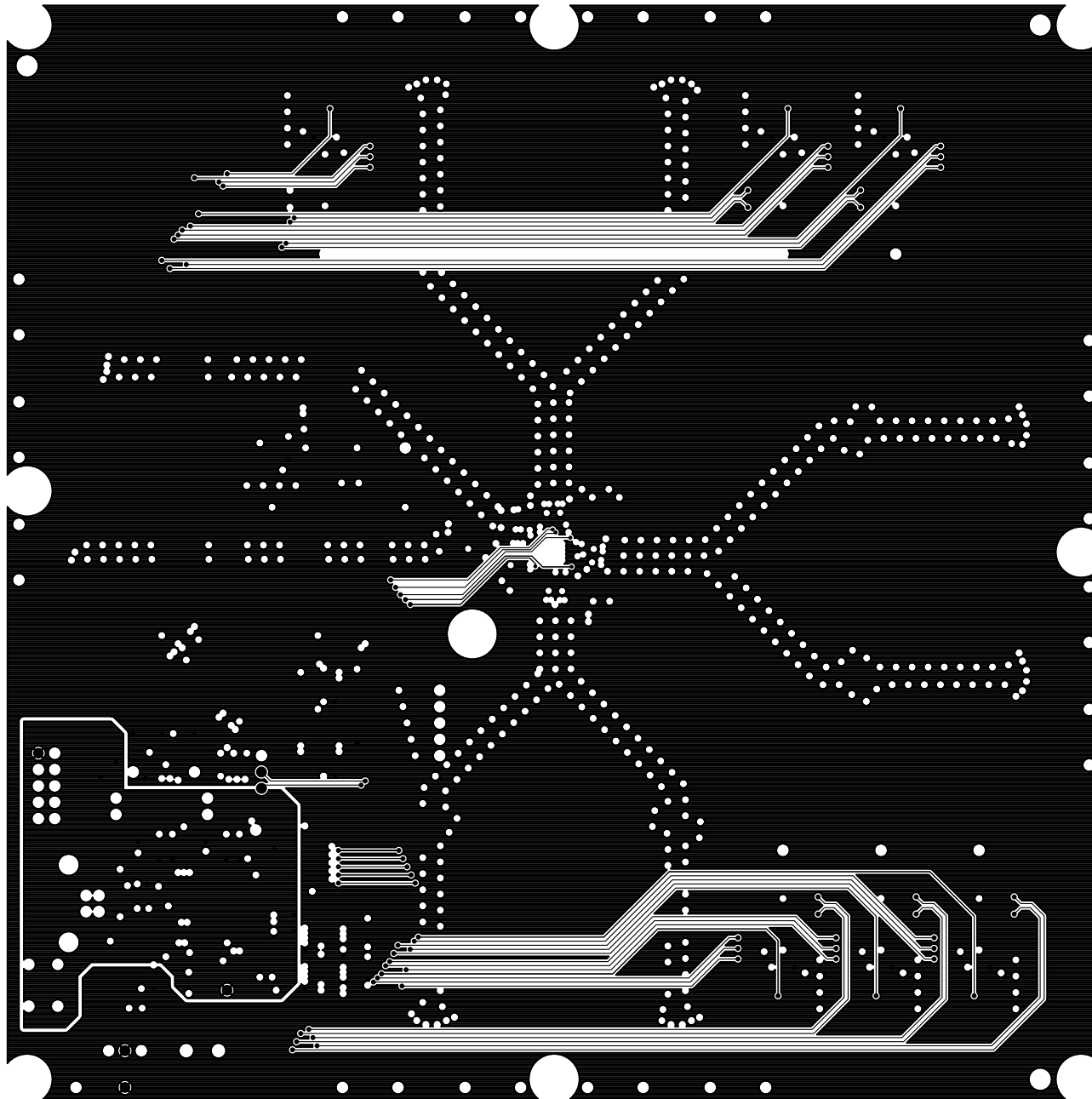
PRIMARY SOLDER MASK



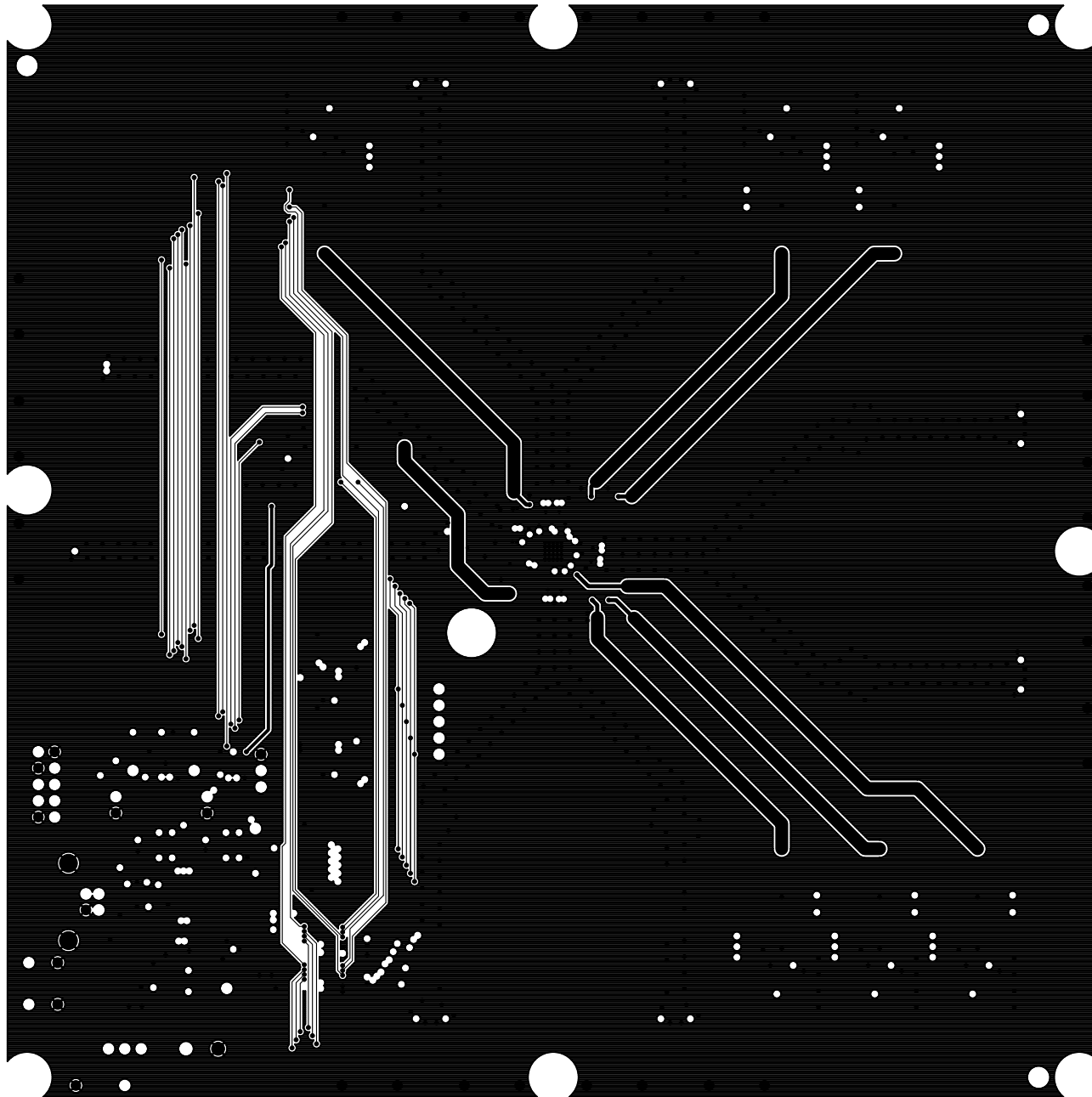
PRIMARY SIDE



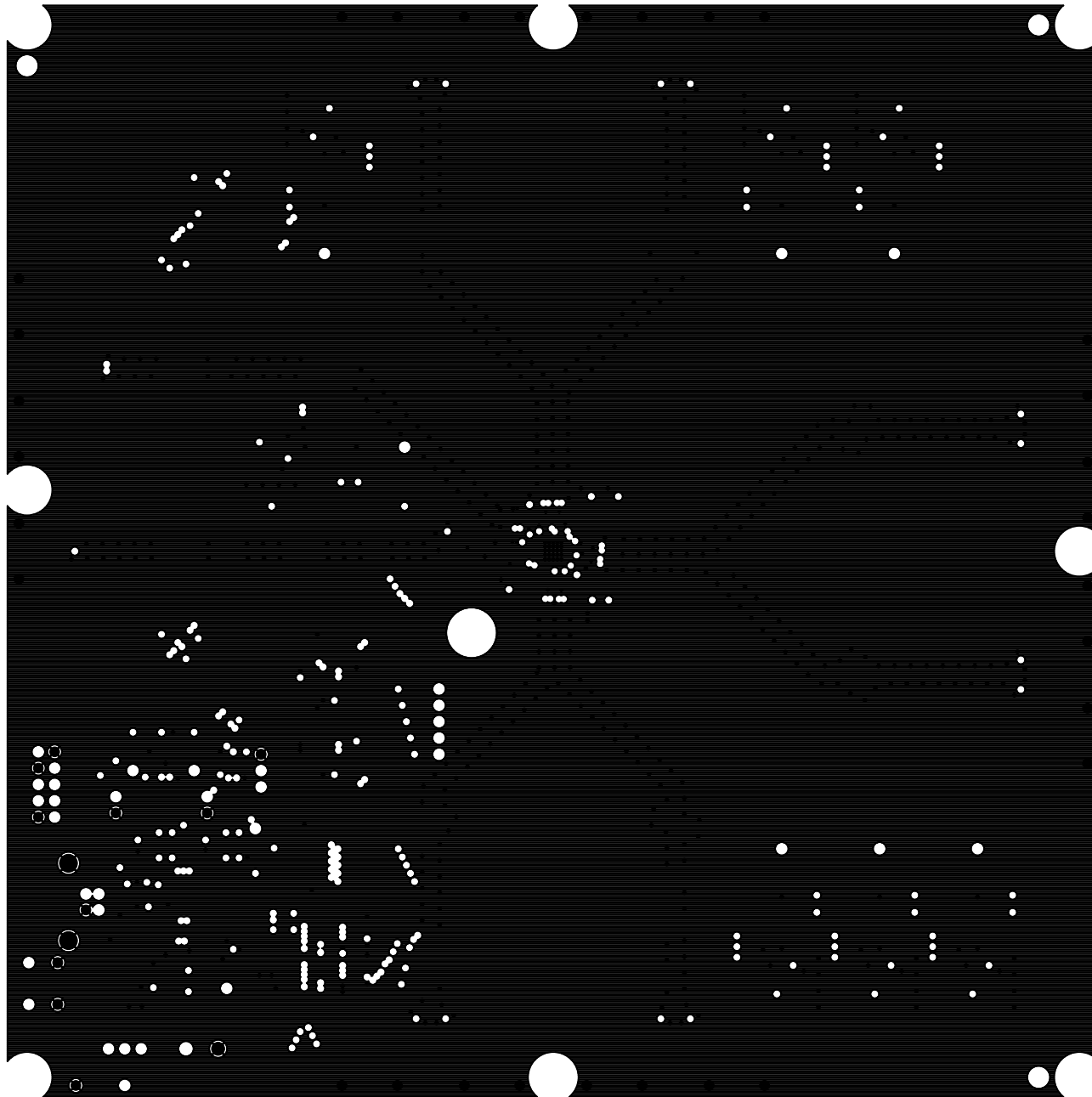


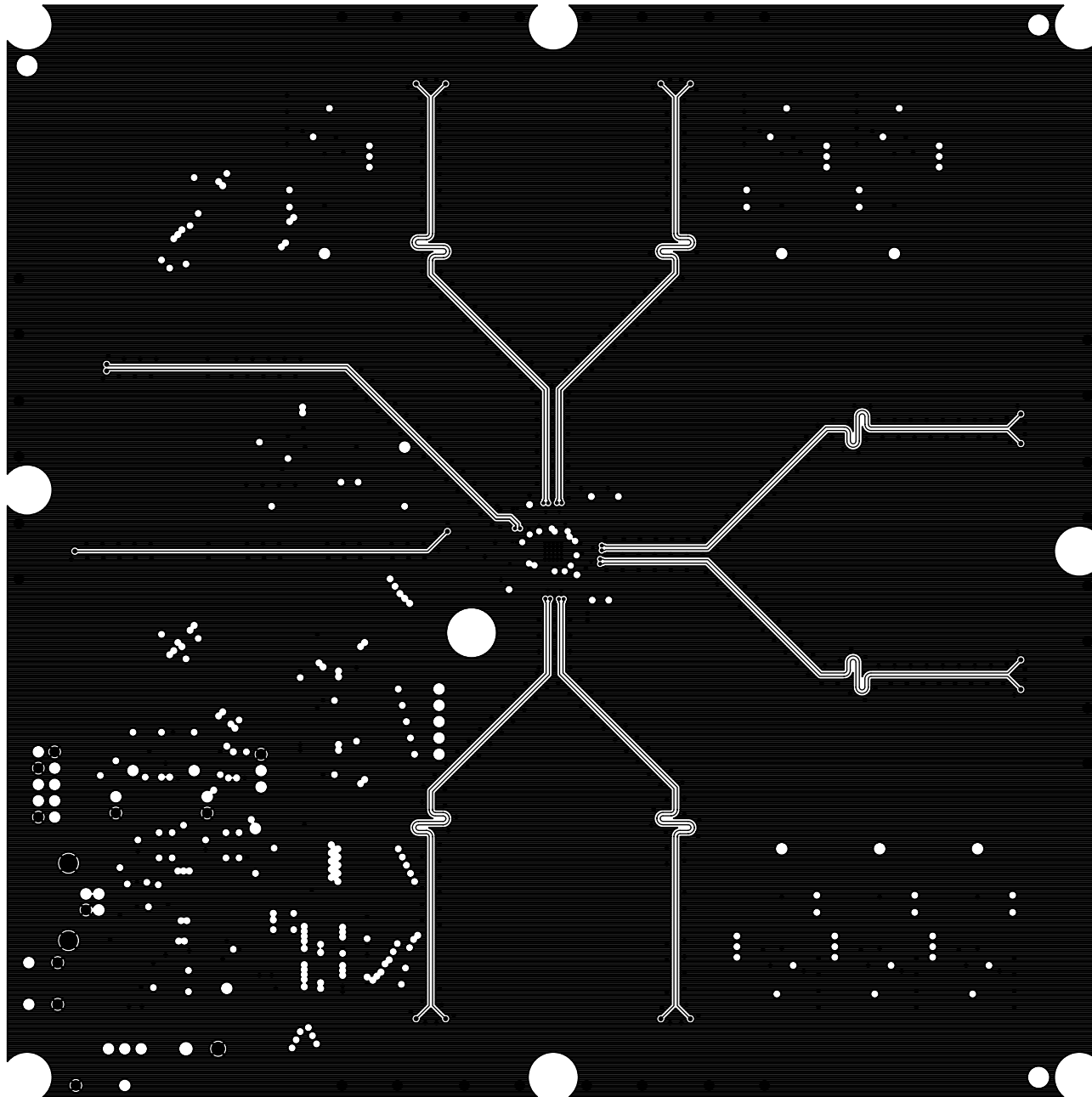


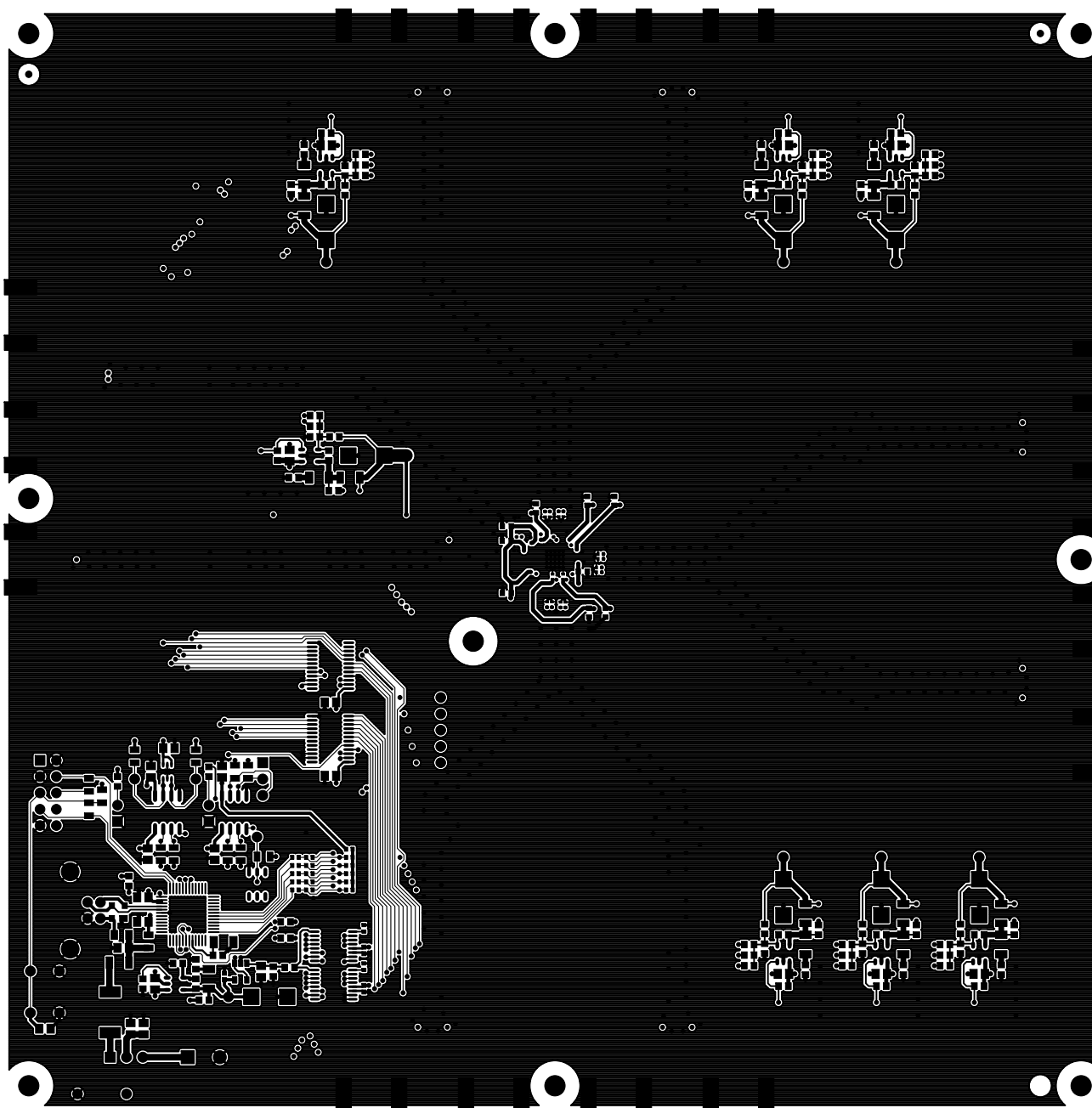
LAYER 04



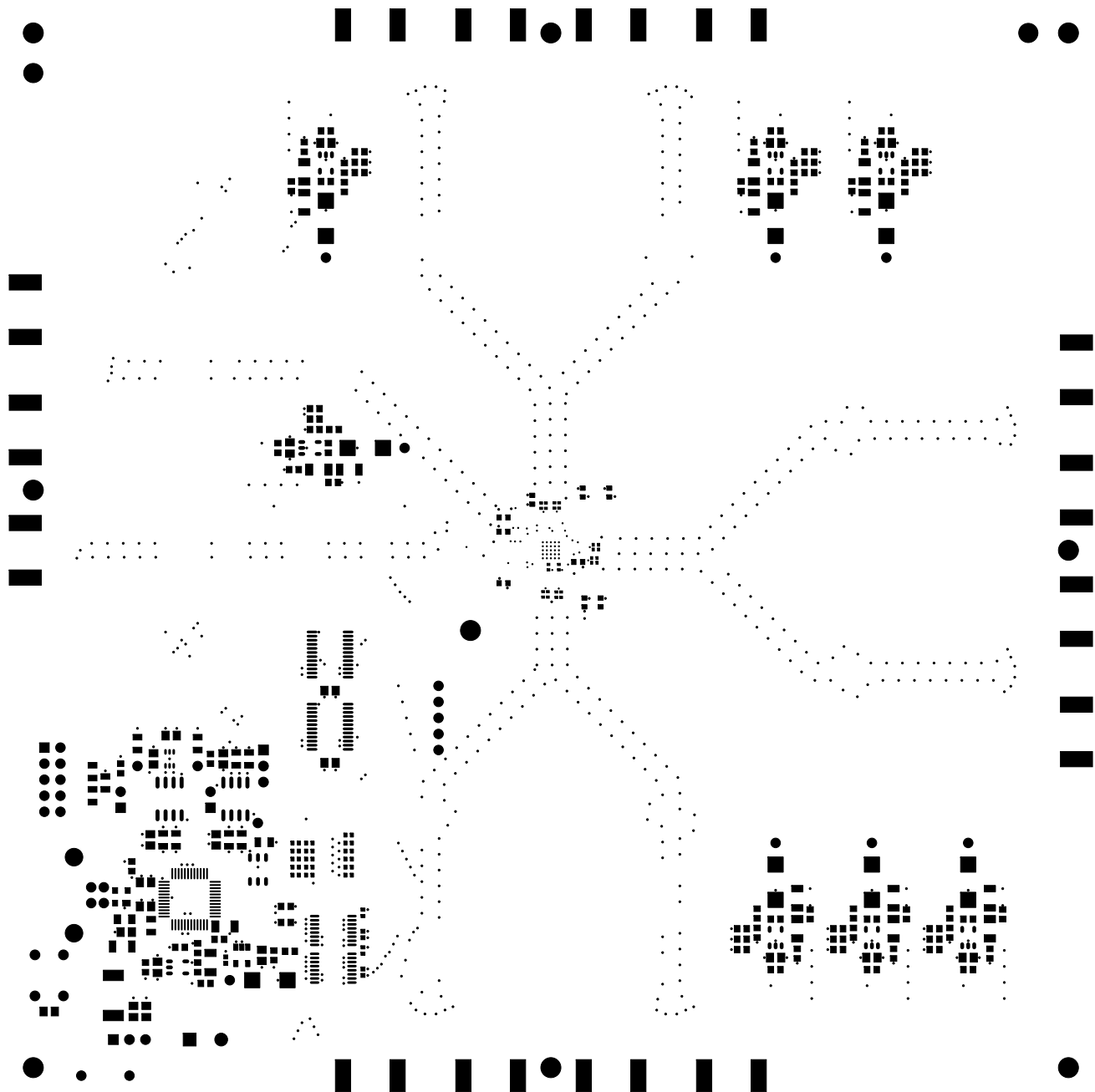
LAYER 05





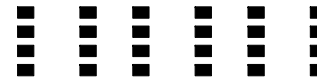
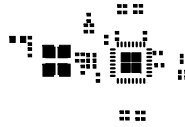


SECONDARY SIDE

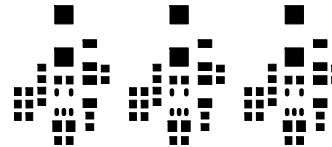
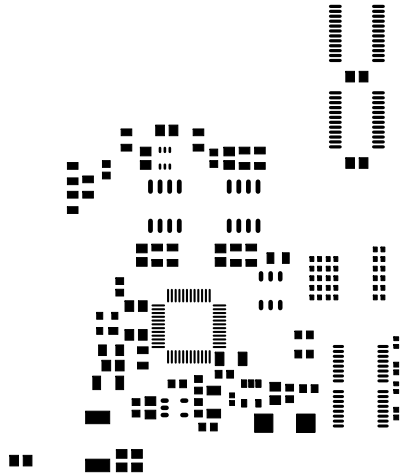
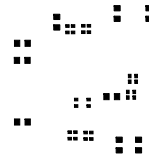
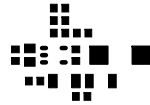
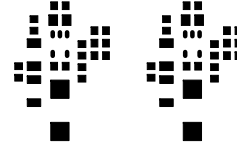
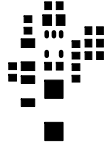


SECONDARY SOLDER MASK

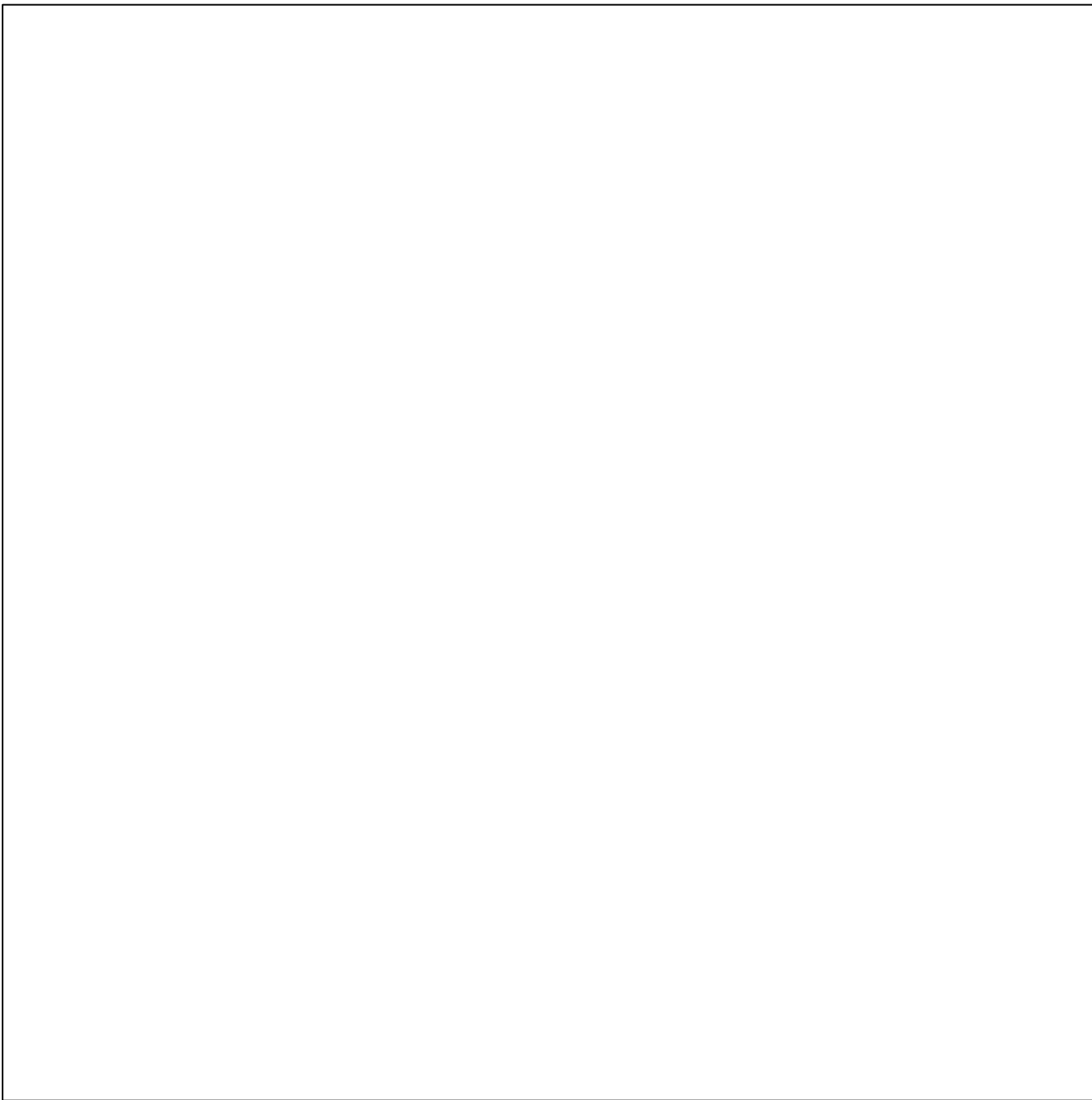


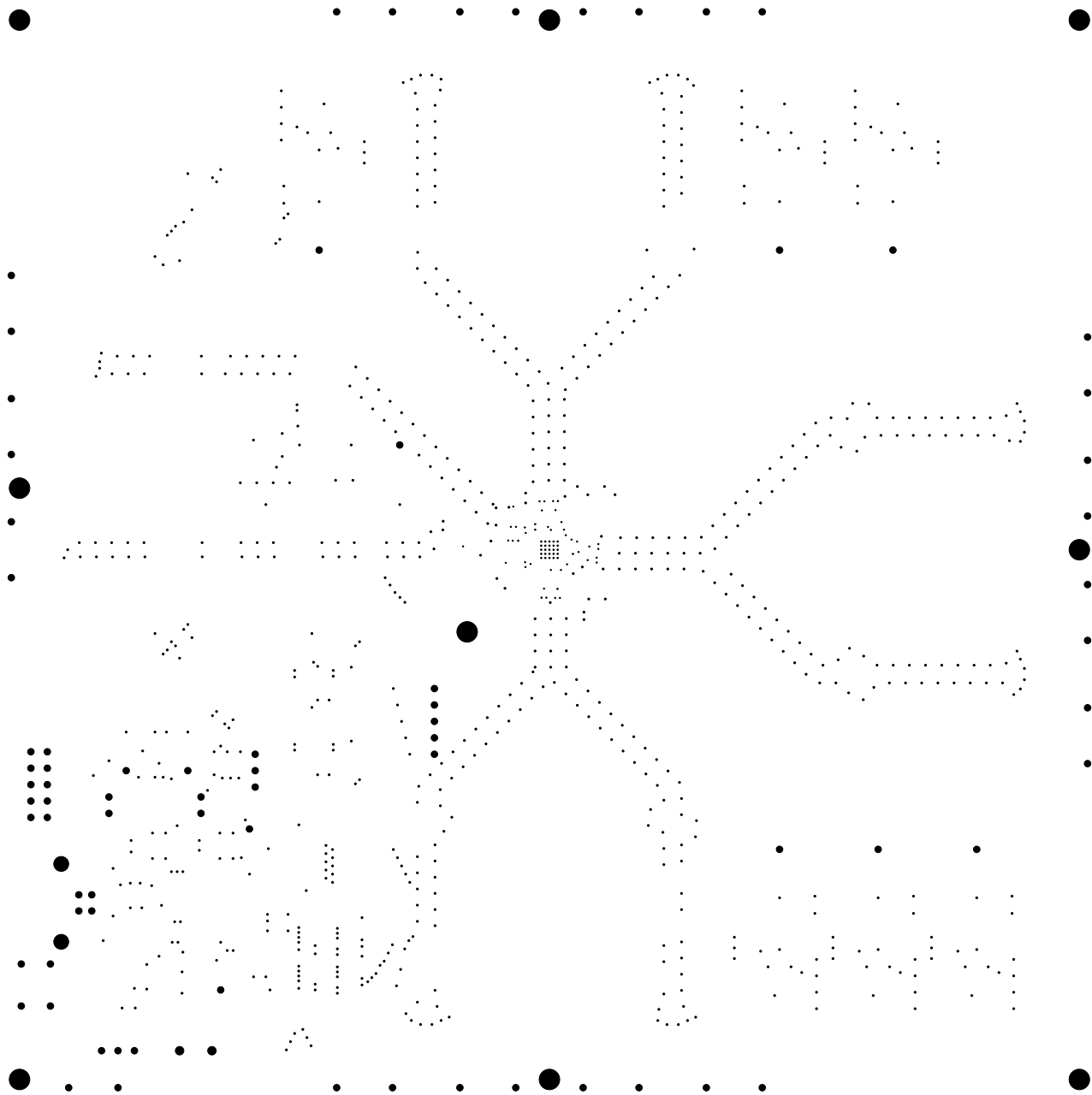


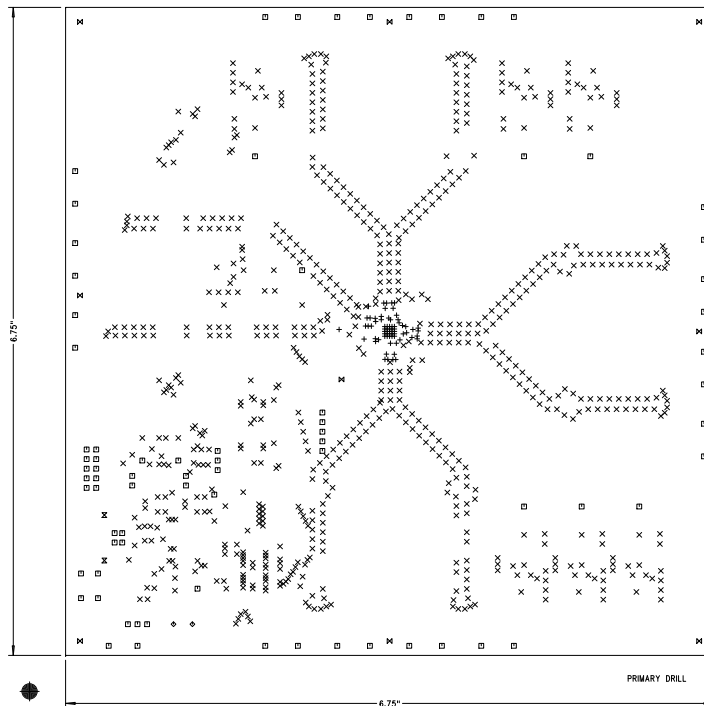
PRIMARY SOLDER PASTE



SECONDARY SOLDER PASTE







NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. LAMINATE AND PREPREG SHALL BE AS PER IPC-4101/26.83.98 WITH A DECOMPOSITION TEMPERATURE \geq 345°C, COLOR, NATURAL.
4. COPPER WEIGHT SHALL BE 0.5 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.0007" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE \pm 0.003".
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE 0.062" \pm 10%.
10. WARP/TWIST SHALL NOT EXCEED 1.0X.
11. FINISH SHALL BE LPL, BLUE SMOGC, ENG BOTH SIDES.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. INTERNAL 0.175MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$.
- EXTERNAL 0.275MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$.
- EXTERNAL 0.660MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$ REF TO L03.
14. VENDOR TO PROVIDE PCB MICRO-SECTION OF COUPON AREA & TDR TEST REPORT.
15. REFERENCE ADDITIONAL FAB NOTES IN FILE README.TXT

LAYER STACKUP		FILE NAMES
PRIMARY SILKSCREEN		5332-AM1-QFN32-CEVB_PSS.PHO
PRIMARY SOLDERMASK		5332-AM1-QFN32-CEVB_PSM.PHO
PRIMARY SIDE		5332-AM1-QFN32-CEVB_PRI.PHO
370HR		5.7MIL THK
GROUND PLANE		5332-AM1-QFN32-CEVB_L02.PHO
370HR		8MIL THK
GROUND PLANE		5332-AM1-QFN32-CEVB_L03.PHO
FR-4 IPC-4101/26.83.98		9.64MIL THK
DIG ROUTE/GND		5332-AM1-QFN32-CEVB_L04.PHO
FR-4 IPC-4101/26.83.98		8MIL THK
DIG ROUTE, VDD0x, GND		5332-AM1-QFN32-CEVB_L05.PHO
FR-4 IPC-4101/26.83.98		9.64MIL THK
GROUND PLANE		5332-AM1-QFN32-CEVB_L06.PHO
370HR		8MIL THK
RF ROUTE/GND		5332-AM1-QFN32-CEVB_L07.PHO
370HR		5.7MIL THK
SECONDARY SIDE		5332-AM1-QFN32-CEVB_SEC.PHO
SECONDARY SOLDERMASK		5332-AM1-QFN32-CEVB_SSM.PHO
SECONDARY SILKSCREEN		5332-AM1-QFN32-CEVB_SSS.PHO
SCALE: NONE		

SIZE	QTY	SYM	PLT	TOOL	TOL
0.008	70	+	P	1	+0/-0.008
0.012	750	X	P	2	+0/-0.012
0.040	76	□	P	3	+/-0.003
0.052	2	◇	P	4	+/-0.003
0.091	2	⊗	P	5	+/-0.003
0.125	9	⊗	N	6	+/-0.003

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DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH DIMENSIONS IN BRACKETS () ARE IN MILLIMETERS INTERPRET DRAWING PER MIL-D-8836		TOLERANCES		NAME: SI5332-AM1-QFN32-EVB	REV: 1.0
HOLE TOLERANCES PER TAB07		SURFACES		DESIGN: TS	DATE: 21JAN2019
DECIMALS	ANGLES	MICROMETERS		LAYOUT: AA	DATE: 25JAN2019
xxx +/-	+/-	PART TO BE FREE OF BURRS		SIZE: C	PART NUMBER:
DRAW DIMS		DRAW DIMS		DO NOT SCALE DRAWING	
SCALE: 1:1		FABRICATION DRAWING		SHEET 1 OF 1	